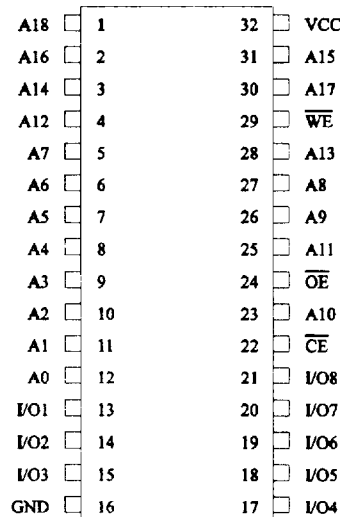


4Mb CMOS STATIC SRAM

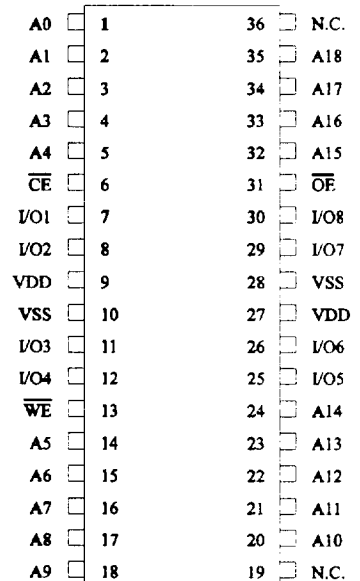
FEATURES

- High density SRAM module
- Organized as 524,288 x 8
- Access time 20 - 35ns
- Low power consumption
Standby: 50mW(typ.)
Operating: 700mW(typ.)
- Power supply voltage 5V±10%
- TTL compatible inputs and outputs
- Fully static operation
- JEDEC standard pinout
- Available Packages:
 - 32 Pin 400 mil SOJ
 - 36 Pin 400 mil SOJ
 - 32 Pin 600 mil DIP

32 Pin Configuration



36 Pin Configuration



Pin Descriptions

- | | | | |
|-----------------|---------------------|-----------------|--------------|
| A0-A18 | Address Inputs | \overline{WE} | Write Enable |
| I/O1-I/O8 | Data Inputs/Outputs | VCC | Power Supply |
| \overline{CE} | Chip Enable | GND | Ground |
| \overline{OE} | Output Enable | | |

GENERAL DESCRIPTION

The ELPAQ EMS512K8E is a high performance 4Mb CMOS SRAM module organized as 524,288 bytes of 8 bits each, using four 1Mb SRAMs and a decoder. The EMS512K8E is packaged in a new small 32 or 36 lead 400 mil wide plastic SOJ, featuring ELPAQs proprietary die stacking technology. The module is also available in a standard 600 mil plastic DIP package.

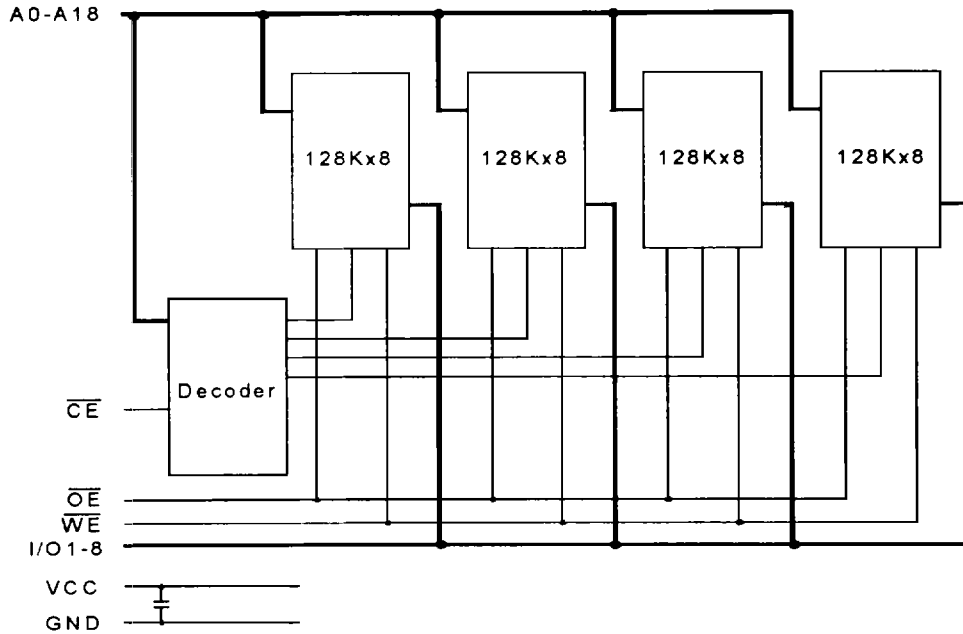
The EMS512K8E is functionally equivalent and plug-in compatible to the 4Mb monolithic SRAM, and can therefore be used in new designs where the 4Mb monolithic will eventually be used.

All inputs and outputs are TTL compatible and the module operates from a single 5V power supply. The EMS512K8E is a fully asynchronous SRAM and requires no clocks for operation. The module is also available in Low Power and Low Power with Data Retention versions for applications where low current and low stand-by voltages are required.

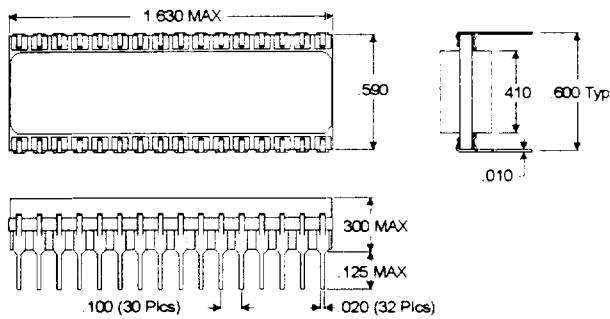
Writing data to the module is accomplished by bringing the chip enable (\overline{CE}) and write enable (\overline{WE}) inputs LOW. Data present on the eight I/O pins (I/O₁ - I/O₈) of the device is then written into the memory location specified by the address inputs (A₀ - A₁₈). Reading data from the device is accomplished by bringing chip enable (\overline{CE}) and (\overline{OE}) LOW while write enable remains inactive or HIGH. The data in the location specified by the address inputs will then appear on the I/O pins.

ELPQ5001

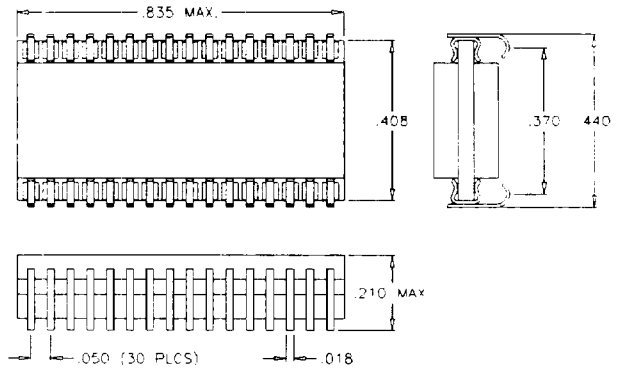
BLOCK DIAGRAM



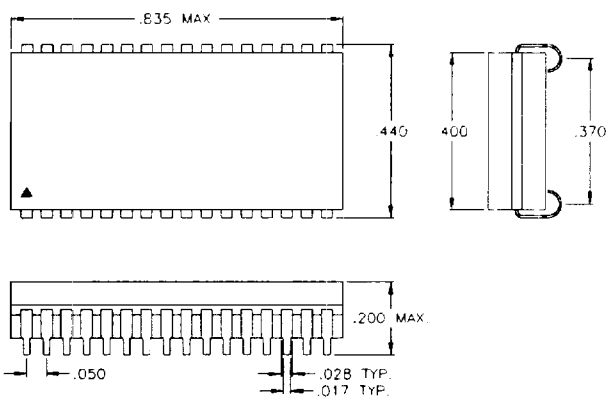
PACKAGE OUTLINES



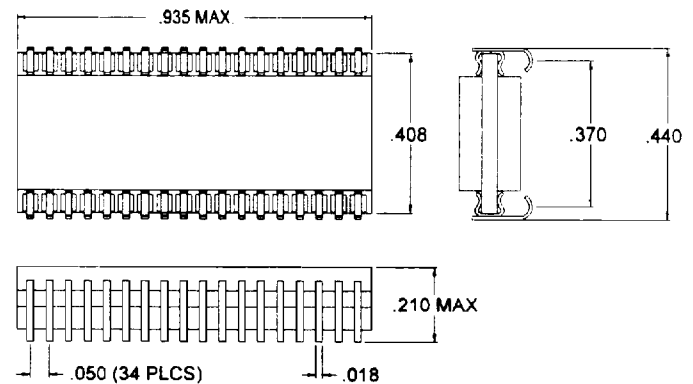
Package Type MO6, 32 Lead .600" Plastic DIP



Package Type MO8, 32 Lead .400" SOJ



Package Type MO7, 32 Lead .400" SOJ



Package Type MO9, 36 Lead .400" SOJ

ABSOLUTE MAXIMUM RATINGS

| | |
|-----------------------------|------------------|
| Storage Temperature | |
| Plastic Packages | -55°C to +125°C |
| Voltage and Current | |
| Supply Voltage | -0.5 to +7.0V |
| Input Voltage | -0.5 to Vcc+0.5V |
| Input/Output Voltage | -0.5 to Vcc+0.5V |
| Allowable Power Dissipation | 1W |
| Soldering Temperature*Time | 230°C * 10s |

OPERATING RANGES

| | |
|------------------------------|-----------------|
| Operating Temperature | |
| Commercial | 0°C to +70°C |
| Industrial | -40°C to +85°C |
| Voltage and Current | |
| Supply Voltage | 4.5 to 5.5V |
| Input High Voltage | 2.2 to Vcc+0.3V |
| Input Low Voltage | -0.3 to 0.8V |

FUNCTIONAL TRUTH TABLE

| \overline{CE} | \overline{OE} | \overline{WE} | Mode | I/O1 - 8 | Vcc Current |
|-----------------|-----------------|-----------------|----------------|----------|-------------|
| H | X | X | Not Selected | High Z | ISB1, ISB2 |
| L | H | H | Output Disable | High Z | ICC |
| L | L | H | Read | Data Out | ICC |
| L | X | L | Write | Data In | ICC |

CAPACITANCE (Ta=25°C, f=1MHz)

| Item | Symbol | Test Conditions | Min. | Typ. | Max. | Unit |
|--------------------------|--------|-----------------|------|------|------|------|
| Input Capacitance | CIN | VIN = 0V | | 30 | 50 | pF |
| Input/Output Capacitance | C/I/O | VI/O = 0V | | 40 | 50 | pF |

Note: This parameter is sample tested and not 100% tested.

DC CHARACTERISTICS (Vcc=5V±10%, Ta=Topr)

| Item | Symbol | Test Condition | Speed | Min. | Typ. | Max. | Unit |
|---------------------------|--------|---|-------|------|------|------|------|
| Input Leakage Current | IIL | VIN=GND or VCC | All | -20 | | 20 | μA |
| Output Leakage Current | IOL | VI/O=GND or VCC, \overline{CE} =VIH OE=VIH or WE=VIL | All | -20 | | 20 | μA |
| Average Operating Current | ICC | Min. Cycle, Iout=0mA VIH=VCC-0.2V, VIL=0.2V | 20 | | 180 | 300 | mA |
| | | | 25 | | 150 | 250 | mA |
| | | | 35 | | 120 | 170 | mA |
| Standby Current | ISB1 | \overline{CE} ≥VCC-0.2V, VIN≥VCC-0.2V | All | | 8 | 20 | mA |
| | ISB2 | \overline{CE} =VIH, VIN=VIL or VIH | All | | | 80 | mA |
| Output High Voltage | VOH | IOH=-4.0mA | All | 2.4 | | | V |
| Output Low Voltage | VOL | IOL=8.0mA | All | | | 0.4 | V |

AC CHARACTERISTICS (Vcc=5V±10%, Ta=Topr)

AC Test Conditions

| Item | Condition |
|-------------------------------|-----------|
| Input Pulse High Level | VIH=3V |
| Input Pulse Low Level | VIL=0V |
| Input Pulse Rise Time | tr=5ns |
| Input Pulse Fall Time | tf=5ns |
| Input and Output Timing Level | 1.5V |
| Output Load | Fig. 1 |

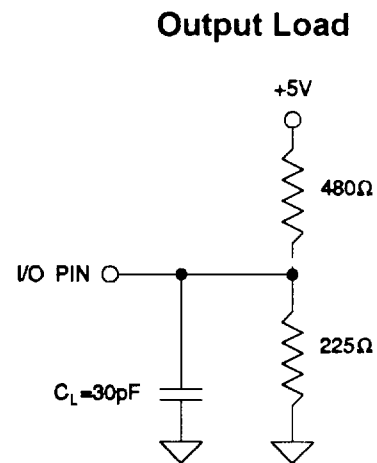


Fig. 1

NOTE: C_L = 5pF for TEHQZ, TELQX, TGHQZ, TGLQX, TWLQZ, TWHQX

Read Cycle

| Item | Symbol | -20 | | -25 | | -35 | | Unit |
|---|--------|------|------|------|------|------|------|------|
| | | Min. | Max. | Min. | Max. | Min. | Max. | |
| Read Cycle Time | TAVAV | 20 | | 25 | | 35 | | ns |
| Address Access Time | TAVQV | | 20 | | 25 | | 35 | ns |
| Chip Enable Access Time | TELQV | | 20 | | 25 | | 35 | ns |
| Output Enable to Output Valid | TGLQV | | 8 | | 8 | | 20 | ns |
| Chip Enable to Output in High Z ⁽¹⁾ | TEHQZ | | 12 | | 12 | | 15 | ns |
| Chip Enable to Output in Low Z ⁽¹⁾ | TELQX | 5 | | 5 | | 5 | | ns |
| Output Disable to Output in High Z ⁽¹⁾ | TGHQZ | | 8 | | 8 | | 12 | ns |
| Output Enable to Output in Low Z ⁽¹⁾ | TGLQX | 0 | | 0 | | 0 | | ns |
| Output Hold from Address Change | TAVQX | 5 | | 5 | | 5 | | ns |

Write Cycle

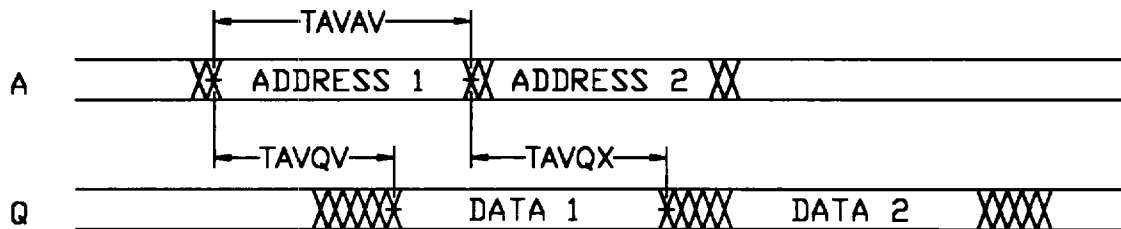
| Item | Symbol | -20 | | -25 | | -35 | | Unit |
|--|--------|------|------|------|------|------|------|------|
| | | Min. | Max. | Min. | Max. | Min. | Max. | |
| Write Cycle Time | TAVAV | 20 | | 25 | | 35 | | ns |
| Address Valid to End of Write | TAVWH | 15 | | 20 | | 30 | | ns |
| Chip Enable to End of Write | TELWH | 17 | | 17 | | 25 | | ns |
| | TWLEH | 17 | | 17 | | 25 | | ns |
| Data to Write Time Overlap | TDVWH | 10 | | 12 | | 15 | | ns |
| | TDVEH | 10 | | 12 | | 15 | | ns |
| Data Hold Time from Write | TWHDX | 0 | | 0 | | 0 | | ns |
| | TEHDX | 0 | | 0 | | 0 | | ns |
| Write Pulse Width | TWLWH | 15 | | 15 | | 20 | | ns |
| | TELEH | 15 | | 15 | | 20 | | ns |
| Address Set-up Time | TAVWL | 0 | | 0 | | 0 | | ns |
| | TAVEL | 0 | | 0 | | 0 | | ns |
| Write Recovery Time | TWHAX | 0 | | 0 | | 0 | | ns |
| | TEHAX | 0 | | 0 | | 0 | | ns |
| Write to Output in High Z ⁽¹⁾ | TWLQZ | | 8 | | 10 | | 15 | ns |
| Output Active from End of Write ⁽¹⁾ | TWHQX | 0 | | 0 | | 0 | | ns |

NOTE 1: This parameter is guaranteed by design and sample tested only.

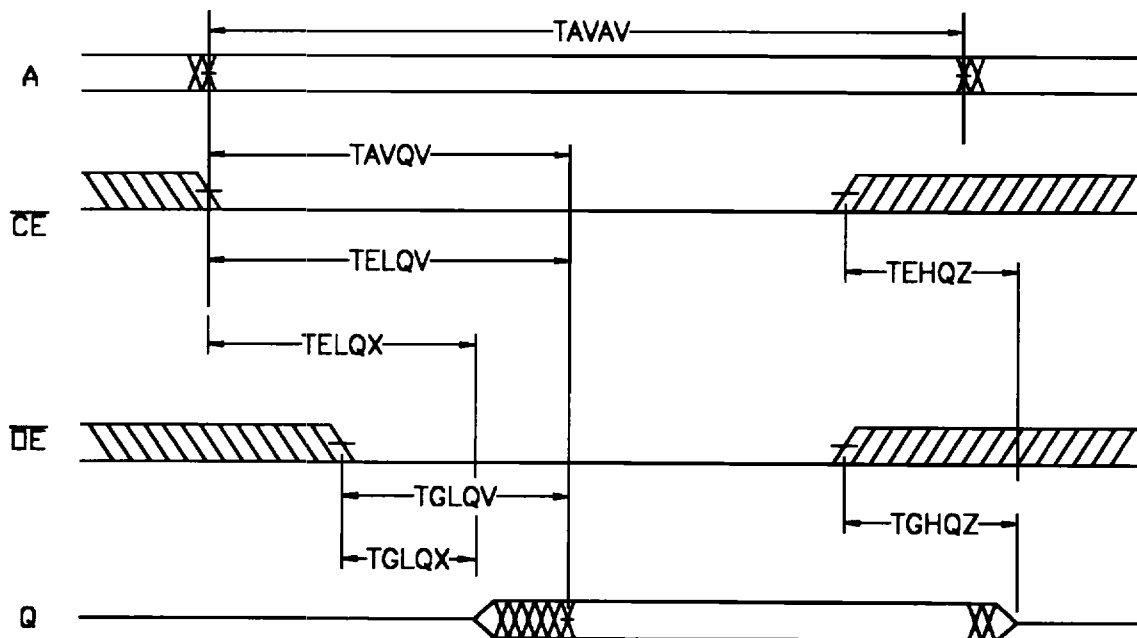
Timing Diagrams

Read Cycle Timing

Read Cycle 1: $\overline{CE}=\overline{OE}=\text{VIL}, \overline{WE}=\text{VIH}$

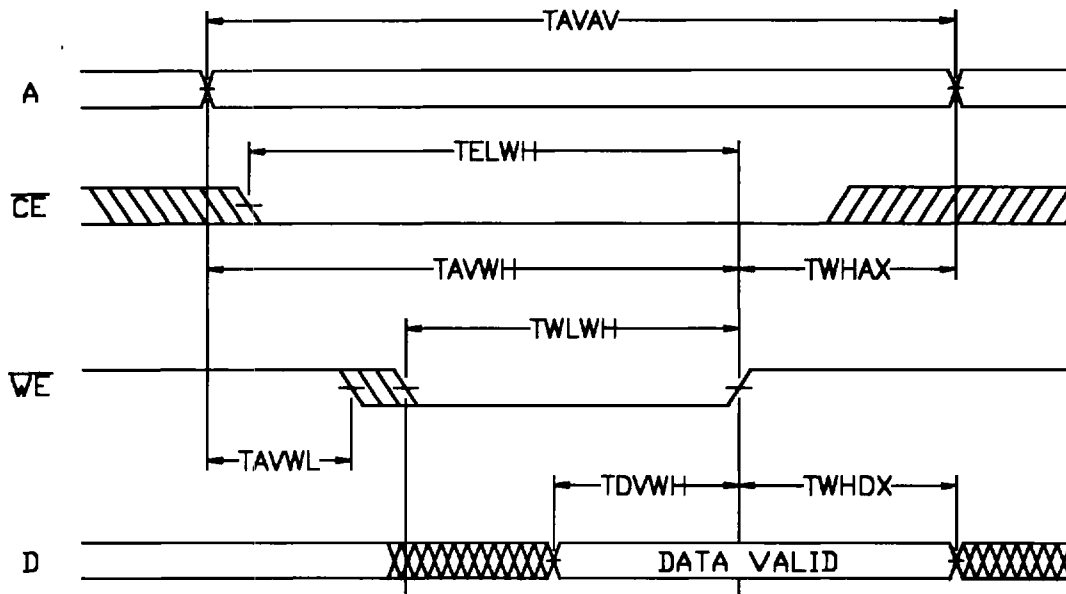


Read Cycle 2: $\overline{WE}=\text{VIH}$

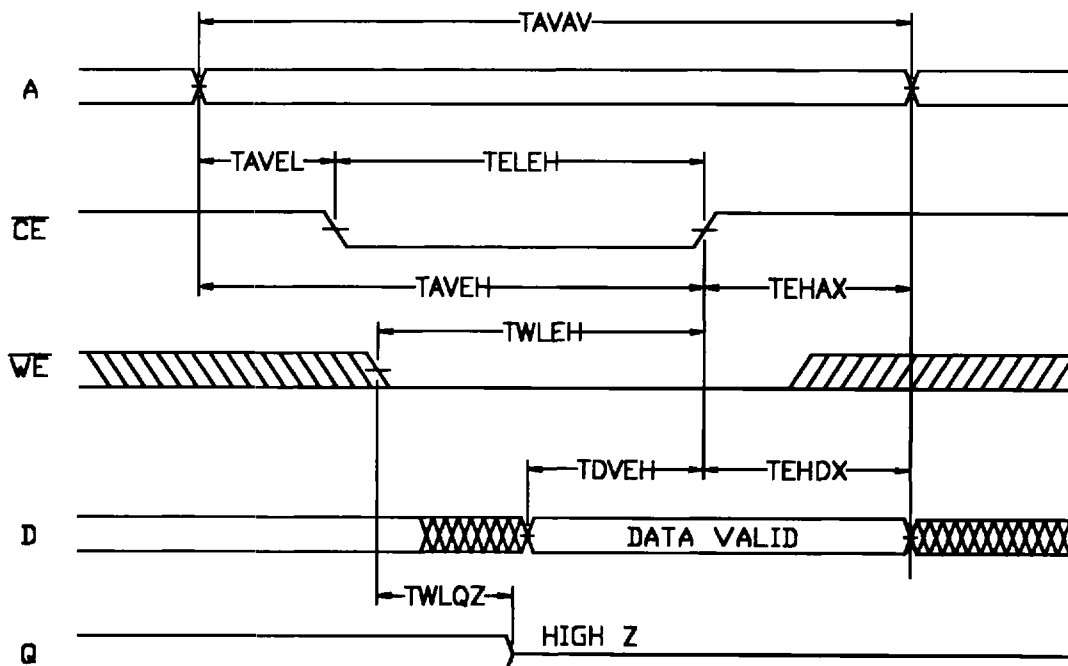


Write Cycle Timing

Write Cycle 1: \overline{WE} Control



Write Cycle 2: \overline{CE} Control



NOTES:**ORDERING INFORMATION**

EMS512K8E

MO7**-20****C****Temperature Range**

C = Commercial (0 - 70°C)

I = Industrial (-40 - +85°C)

Speed

-20 = 20ns Access Time

-25 = 25ns Access Time

-35 = 35ns Access Time

Package

MO6 = .600" 32 Lead Plastic DIP

MO7 = .400" 32 Lead Plastic SOJ, Type I *

MO8 = .400" 32 Lead Plastic SOJ, Type C *

MO9 = .400" 36 Lead Plastic SOJ, Type C *

* Also available in reverse leaded configuration for over-under applications. MO7R, MO8R, MO9R.